Newsletter

Volume 4, Issue 1
December 2023

Edge AI Project General Assembly, 16 October 2023, Athens, Greece

The EdgeAI consortium organised the annual general assembly on 16 October 2023 in Athens, Greece, with the participation of more than 60 representatives from the project beneficiaries, affiliated entities, and associated partners.

The main objective of the general assembly was to bring together the members of the EdgeAI consortium to discuss the status of the project activities and the contractual documents, including the consortium agreement (CA).

The presentations addressed the developments in the twenty project demonstrators structured under five value chains, with the discussions focusing on the deliverables, highlighting the activities on the functional and non-functional requirements for each demonstrator, the progress of work, and the challenges.

The presentations included an overview of the main activities of the ecosystem orchestration: communication, dissemination, exploitation, and standardisation. They focused on the guidelines for implementing these activities until the end of the year and prepared the plans for the following year.

The EdgeAI general assembly concluded with a questions and answers session that reflected the issues of interest for the consortium beneficiaries.

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European Conference on EDGE AI Technologies and Applications – EEAI 2023, 17-19 October 2023, Athens, Greece

On 17-19 October 2023, at the Royal Olympic Hotel, Athens, Greece, the EdgeAI project was the main co-organiser of the European Conference on EDGE AI Technologies and Applications – EEAI 2023, a European venue for sharing the latest scientific research and industry results employing edge AI technologies and applications.

The event was co-organised by the large-scale Chips Joint Undertaking (JU) EdgeAI project in collaboration with the CLEVER, REBECCA, TRISTAN, NEUROKIT2E, LoLiPoP IoT projects, the ECSEL JU ANDANTE, AI4CSM, AI4DI, TEMPO projects and the INSECTT projects to deliver a platform to exchange knowledge and ideas among experts and professionals interested in advances in edge AI circuits and device design, edge AI hardware architectures, industrial edge AI technologies, toolchains, and applications.

The conference was supported by the industry associations AENEAS, EPoSS, and INSIDE. EPoSS and INSIDE used the opportunity to organise, on 18 October 2023, a session dedicated to the second European workshop on the future of edge AI to identify a potential roadmap for European research and innovation in the domain of edge AI to be used for future focus topics of the Chips Joint Undertaking and inspire other European programs.

The EEAI 2023 was organised as a combination of three plenary sessions with specific keynote speeches and a session dedicated to pitch presentations from the participating projects.

The technical presentations were clustered under sixteen sessions covering ten distinct edge AI technology blocks and five application areas (agri-food and beverages, intelligent mobility systems, autonomous vehicle domains, digital society, and digital industry).

The sessions addressing intelligent mobility systems and autonomous vehicle domain applications were conducted in collaboration with the ECSEL JU AI4CSM project.

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The conference content covered the edge AI technology stack following emerging research and innovation from hardware to software, edge AI frameworks, architectures, algorithms, data types, and methods to applications. The presentations and the technical sessions highlighted the expansion of the micro-, deep-, and meta-edge continuum as part of the novel distributed AI-based computing architectures supporting emerging intelligent autonomous systems and applications across various industrial sectors.

The event gathered more than 130 delegates from academia, researchers, and industry practitioners who exchanged the latest fundamental advances in state-of-the-art practices of edge AI technologies and applications, identifying emerging research topics and defining the future of edge AI research and innovation.

The European Conference on EDGE AI Technologies and Applications was a success, with the participants appreciating the quality of the technical presentations, sessions' content, networking opportunities, engagement with fellow participants, venue and the overall organisation.

The conference achieved its aim to serve as an innovative edge AI platform for exchanging ideas and concepts and feature several leading voices in research and industry supporting the integration of edge AI technologies for advancing future industrial applications.

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Chips Joint Undertaking (JU) Launch Event, 30 November - 1 December 2023, Brussels, Belgium

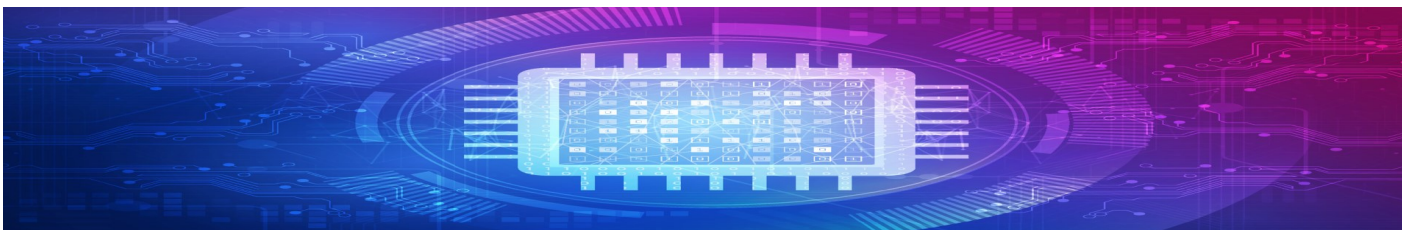
The Chips Joint Undertaking (JU) was launched on 30 November – 1 December 2023 in Brussels, Belgium, with over 800 participants representing experts and practitioners in the electronic components and systems sector. The event celebrated the official inauguration of Chips JU and provided insights into its objectives and strategic roadmap.

The Chips JU is the leading implementer of the Chips for Europe Initiative (expected total budget of €15.8 billion until 2030). The Chips JU goal is to strengthen Europe's semiconductor ecosystem and economic security by managing an expected budget of nearly €11 billion by 2030, provided by the EU and participating states.

The European Commission representatives highlighted that the Chips JU would reinforce the European semiconductor ecosystem and Europe's technological leadership and bridge the gap between research, innovation, and production, thereby facilitating the commercialisation of innovative ideas. It was reiterated that the initiative will, among others, deploy pilot lines for which the first calls were announced with €1.67 billion of EU funding. The funds from Member States are expected to match the amount to reach €3.3 billion, plus additional private funds.

The EdgeAI project participated in the Chips JU launch event "Walk of Fame" exhibition aimed to celebrate and highlight outstanding projects that significantly impact the industry. The exhibition allowed EdgeAI consortium members to network, share knowledge, and discuss possible collaborations with other project participants, industry leaders, policymakers, experts, and innovators.

The Chips JU "Walk of Fame" exhibition proved to be an outstanding arena where the EdgeAI project showcased the project activities, allowing attendees to witness the innovative solutions the project has to offer as the EdgeAI communication team provided a captivating experience centered around video and oral presentations, offering a unique and informative perspective of edge AI technologies and applications.



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Driving Next-Gen Edge AI Technologies Workshop, 17 January 2024, Munich, Germany

The EdgeAI consortium took the initiative to organise the "Driving Next-Gen Edge AI Technologies" workshop on 17 January 2024 as part of the HiPEAC 2024 Conference, 17-19 January 2024, to be held in Munich, Germany.

The workshop aims to address the latest developments in the implementation of edge AI technologies and present and discuss the advances in intelligent embedded devices across the edge AI computing continuum from micro- to deep- and meta-edge. The aim is to advance the field of smart embedded devices by systematically evaluating and comparing technologies for edge AI. The event plans to address these challenges head-on, bringing together a diverse community of experts, researchers, and industry leaders to tackle the intricacies of benchmarking in edge AI.

The workshop is co-organised by the large-scale Chips JU EdgeAI, ANDANTE, REBECCA, CLEVER, NEUROKIT2E, and Horizon Europe dAIEDGE projects to exchange ideas for providing a set of reference comprehensive benchmarking solutions by bringing together a diverse community of experts, researchers, and industry leaders to collectively tackle the intricacies of benchmarking in edge AI.

More than 96 participants are registered for the workshop, and several EdgeAI beneficiaries have presentations and are attending the event.

Join the workshop to experience an innovative and transformative journey firsthand as the participant aims to shape the future of edge AI, ensuring its efficiency and reliability in the dynamic edge computing landscape.

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https://edge-ai-tech.eu/

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EdgeAI Key Facts

Start: 01 December 2022

Duration: 37 months

Budget: 35,43 M€

Coordinator: SINTEF AS

Consortium: 49 partners

Consortium

SINTEF, Infineon, ams OSRAM, SoftwareCUBE, TU/e, imec, NXP, GNT, NEURO Controls, COGNITION FACTORY, IMST, Universität zu Lübeck, netcompany intrasoft, ST life.augmented, VRANKEN POMMERY, TECHNEXT, cea, GRENOBLE INP UGA, Université de Reims Champagne-Ardenne, cnrs, Université Polytechnique Hauts-de-France, Χαροκοπειο Πανεπιστημιο Harokopio University, scmgroup, HTS High Technology Systems, Intelligent Machines IoT & Cyber Physical Systems DeepSensing S.R.L., Xtremion, Università degli Studi di Cagliari, Alma Mater Studiorum Università di Bologna, Università degli Studi di Milano, Elektronikas un datorzinātņu institūts Institute of Electronics and Computer Science, signify, Technolution, almende, TU/e, Fredrikstad energi, NxtEnergy, PROLUX, nxtech, ITML, CONVERGENCE

Disclaimer

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